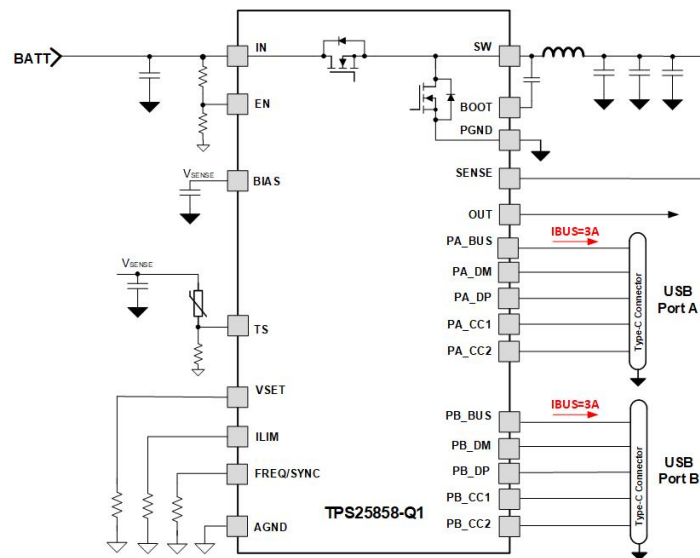


Small-Size and Thermal-Optimization Rated 30-W Automotive Dual USB Type-C® Charger Reference Design

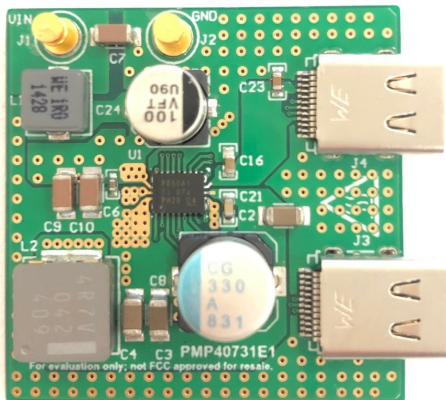


Description

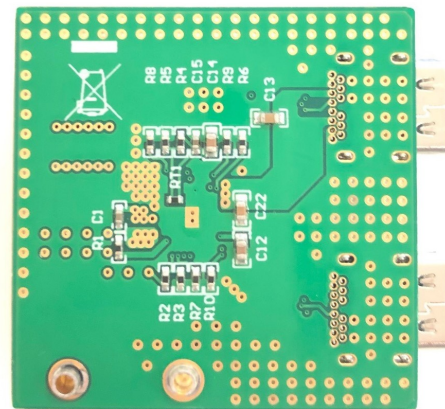
This reference design is a small size and thermal optimization design for automotive USB Type-C® charger with dual 15-W output. The TPS25858-Q1 device is a cost-competitive DC/DC regulator and dual USB Type-C® port controller. The efficiency is 92.83% at dual 15-W output. Programmable cable droop compensation helps portable devices charge at optimum current and voltage under heavy loads. A negative temperature coefficient (NTC) thermistor is implemented for intelligent thermal management to reprogram the output voltage in overtemperature condition.



Block Diagram



Top Photo



Bottom Photo

1 Test Prerequisites

1.1 Design Requirements

Table 1-1. Design Requirements

| Parameter | Specifications |
|-------------------------------|----------------------|
| Input Voltage | 13.5 V _{DC} |
| PA_BUS Output Voltage | 5.17 V _{DC} |
| PA_BUS Maximum Output Current | 3 A |
| PB_BUS Output Voltage | 5.17 V _{DC} |
| PB_BUS Maximum Output Current | 3 A |
| Switching Frequency | 400 kHz |

1.2 Required Equipment

- Multimeter (Voltage): Fluke 287C
- Multimeter (current): Fluke 287C
- DC Source: Chroma 62006P-100-25
- E-Load: Chroma 63105A module
- Oscilloscope: Tektronix DPO4104B
- Electrical Thermography: Fluke TiS55
- Thermal Data Acquisition: Agilent 34970A
- Temperature Chamber: ESPEC BTZ-175E

1.3 Dimensions

The dimension of this board is 35 mm (length) × 35 mm (width).

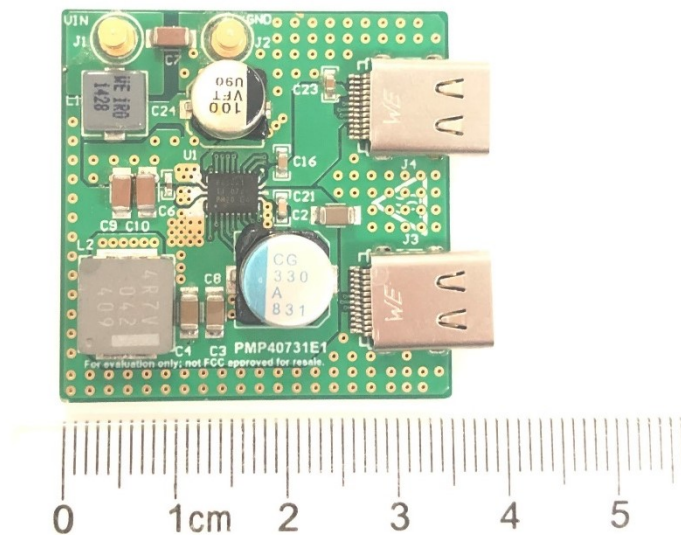


Figure 1-1. Dimension

2 Testing and Results

2.1 Efficiency Graphs

Efficiency is shown in the following figure.

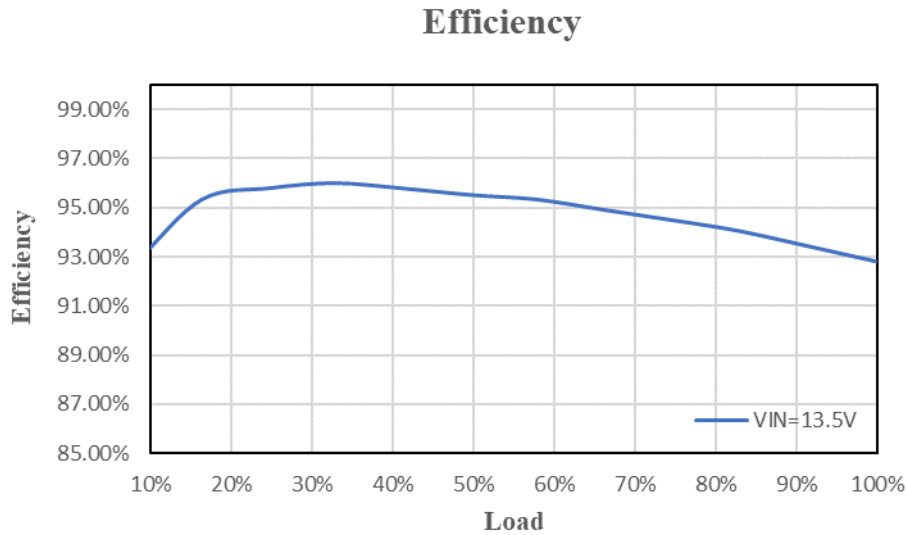


Figure 2-1. Efficiency Graph

2.2 Efficiency Data

Efficiency data is shown in the following table.

| VIN (V) | IIN (A) | VPA_BUS (V) | IPA_BUS (A) | VPB_BUS (V) | IPB_BUS (A) | Eff |
|---------|---------|-------------|-------------|-------------|-------------|--------|
| 13.499 | 0.0290 | 5.1586 | 0.0000 | 5.1586 | 0.0000 | 0.00% |
| 13.502 | 0.2270 | 5.1616 | 0.2492 | 5.1616 | 0.2484 | 83.80% |
| 13.502 | 0.4275 | 5.1678 | 0.4989 | 5.1678 | 0.4981 | 89.26% |
| 13.507 | 0.6268 | 5.1726 | 0.7484 | 5.1727 | 0.7477 | 91.41% |
| 13.500 | 0.8279 | 5.1771 | 0.9983 | 5.1772 | 0.9974 | 92.44% |
| 13.503 | 1.0308 | 5.1818 | 1.2483 | 5.1819 | 1.2499 | 93.01% |
| 13.505 | 1.2345 | 5.1868 | 1.4975 | 5.1870 | 1.4999 | 93.25% |
| 13.499 | 1.4413 | 5.1922 | 1.7474 | 5.1923 | 1.7495 | 93.32% |
| 13.500 | 1.6483 | 5.1976 | 1.9970 | 5.1980 | 1.9992 | 93.35% |
| 13.500 | 1.8588 | 5.2028 | 2.2470 | 5.2035 | 2.2489 | 93.22% |
| 13.503 | 2.0742 | 5.2063 | 2.4994 | 5.2070 | 2.5016 | 92.97% |
| 13.496 | 2.2874 | 5.2023 | 2.7491 | 5.2030 | 2.7516 | 92.70% |
| 13.498 | 2.5020 | 5.1980 | 2.9992 | 5.1987 | 3.0016 | 92.37% |

2.3 Load Regulation

Load regulation is shown in the following figure.

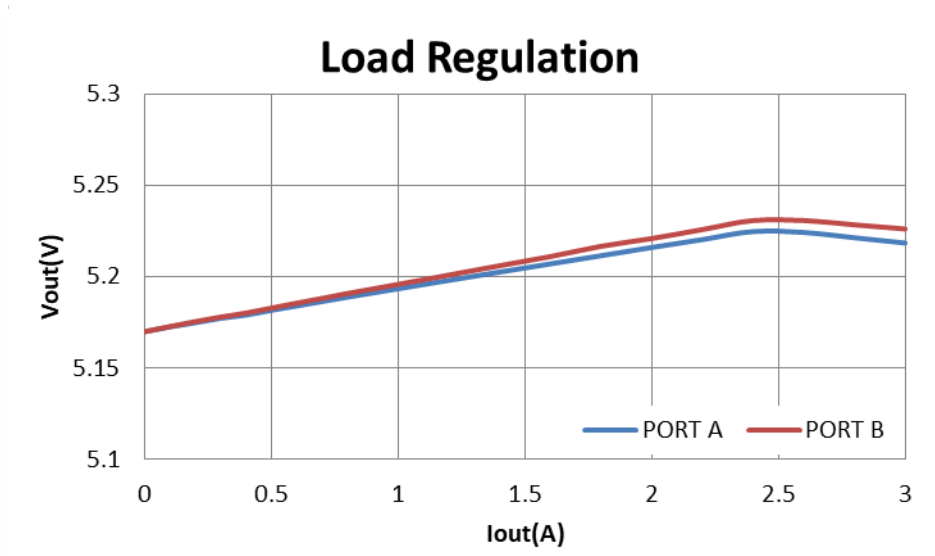


Figure 2-2. Load Regulation

2.4 Thermal Images

Thermal images are shown in the following figures. The ambient temperature is 25°C, and the thermal images were taken with all outputs at a full load of 3 A. The controller was operated for approximately 2 hours before thermal images were taken to ensure thermal steady state was reached.

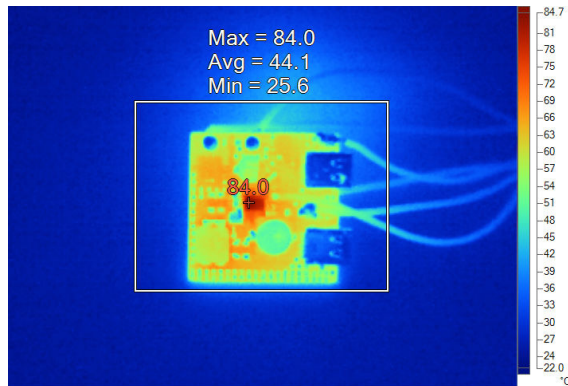


Figure 2-3. Top Side

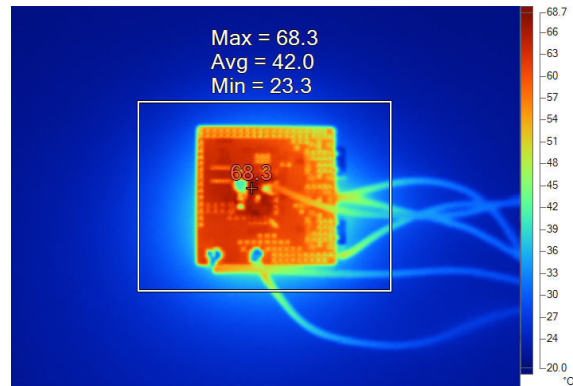
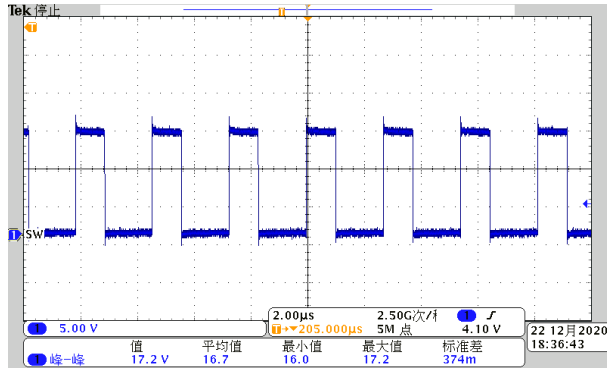


Figure 2-4. Bottom Side

3 Waveforms

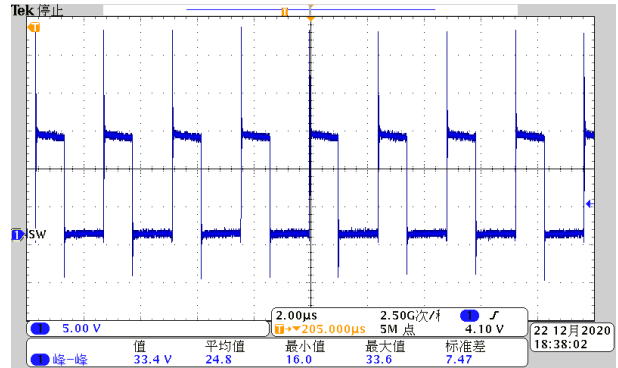
3.1 Switching

Switching behavior is shown in the following figures.



CH1: V_{SW}

Figure 3-1. 13.5-V Input, 5.17-V No-Load

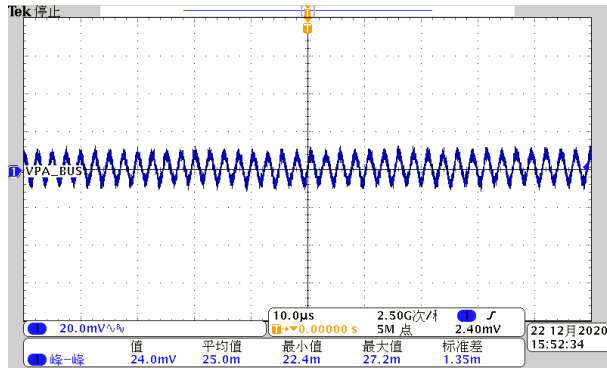


CH1: V_{SW}

Figure 3-2. 13.5-V Input, 5.17-V Full Load

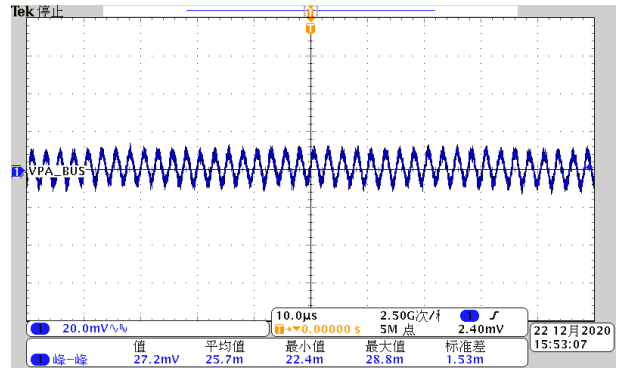
3.2 Output Voltage Ripple

Output voltage ripple is shown in the following figures.



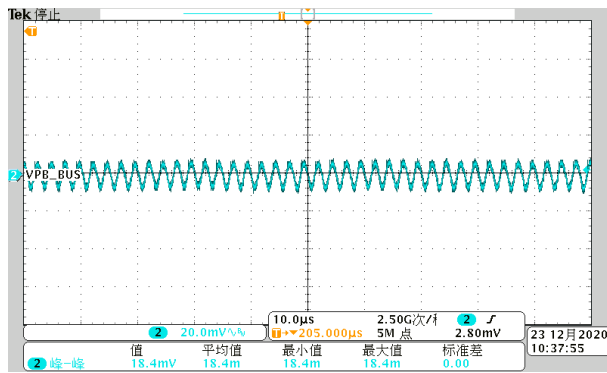
CH1: V_{PA_BUS}

Figure 3-3. Port A: 13.5-V Input, 5.17-V No-Load



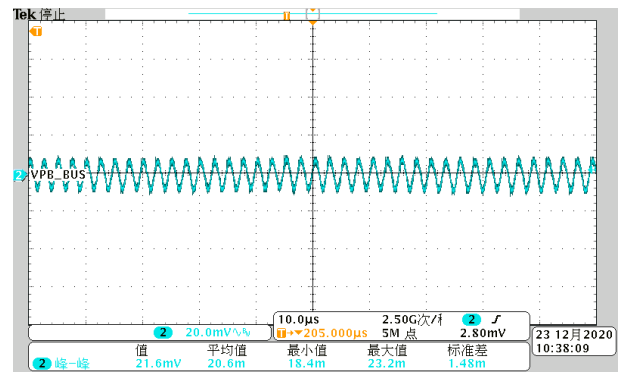
CH1: V_{PA_BUS}

Figure 3-4. 13.5-V Input, 5.17-V 3-A Load



CH2: V_{PB_BUS}

Figure 3-5. 13.5-V Input, 5.17-V No Load

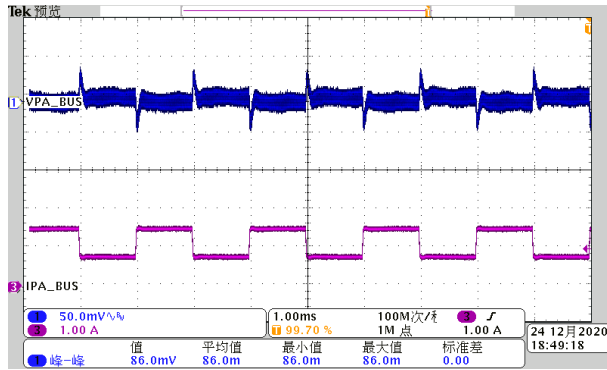


CH2: V_{PB_BUS}

Figure 3-6. 13.5-V Input, 5.17-V 3-A Load

3.3 Load Transients

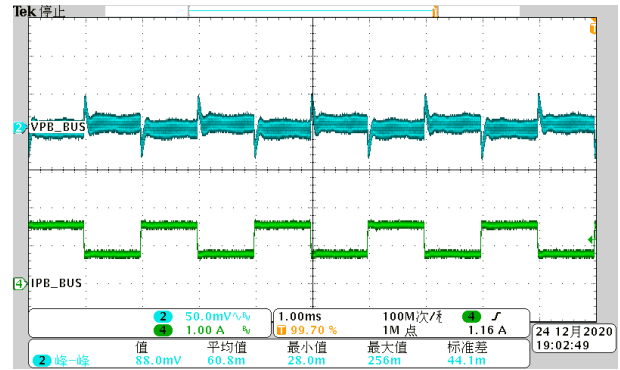
The load transient response is shown in the following figures. The slew rate is set to 2.5 A/ μ s for the test.



CH1: V_{PA_BUS}

CH3: I_{PA_BUS}

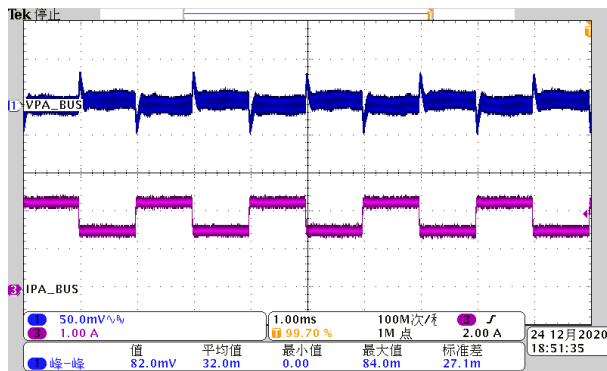
Figure 3-7. Port A: 13.5-V Input, 0.75 A→1.5 A



CH2: V_{PB_BUS}

CH4: I_{PB_BUS}

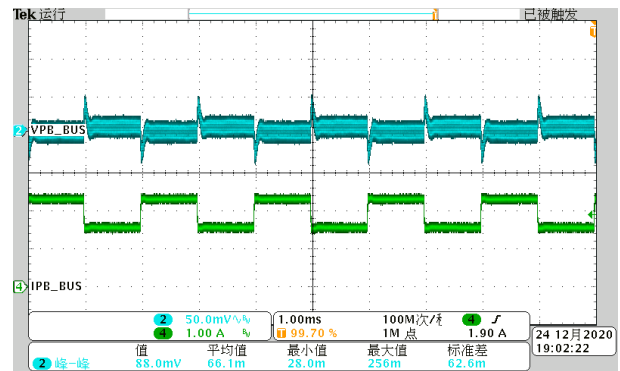
Figure 3-8. Port B: 13.5-V Input, 0.75 A→1.5 A



CH1: V_{PA_BUS}

CH3: I_{PA_BUS}

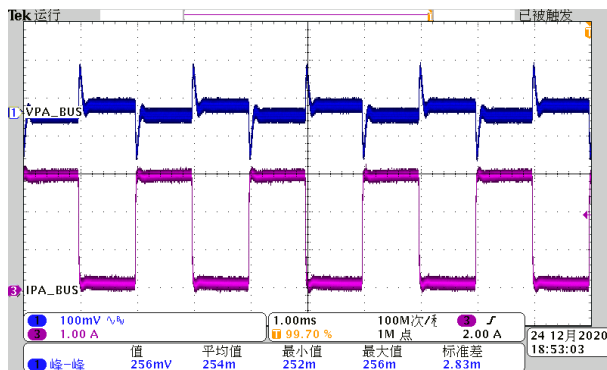
Figure 3-9. Port A: 13.5-V Input, 1.5 A→2.25 A



CH2: V_{PB_BUS}

CH4: I_{PB_BUS}

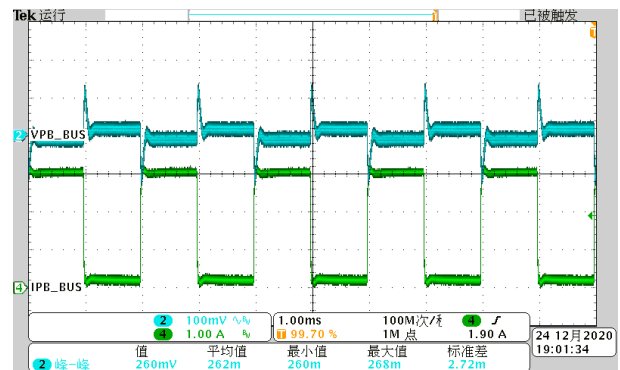
Figure 3-10. Port B: 13.5-V Input, 1.5 A→2.25 A



CH1: V_{PA_BUS}

CH3: I_{PA_BUS}

Figure 3-11. Port A: 13.5-V Input, 0.15 A→3 A



CH2: V_{PB_BUS}

CH4: I_{PB_BUS}

Figure 3-12. Port B: 13.5-V Input, 0.15 A→3 A

3.4 Start-up Sequence

Start-up behavior is shown in the following figure.

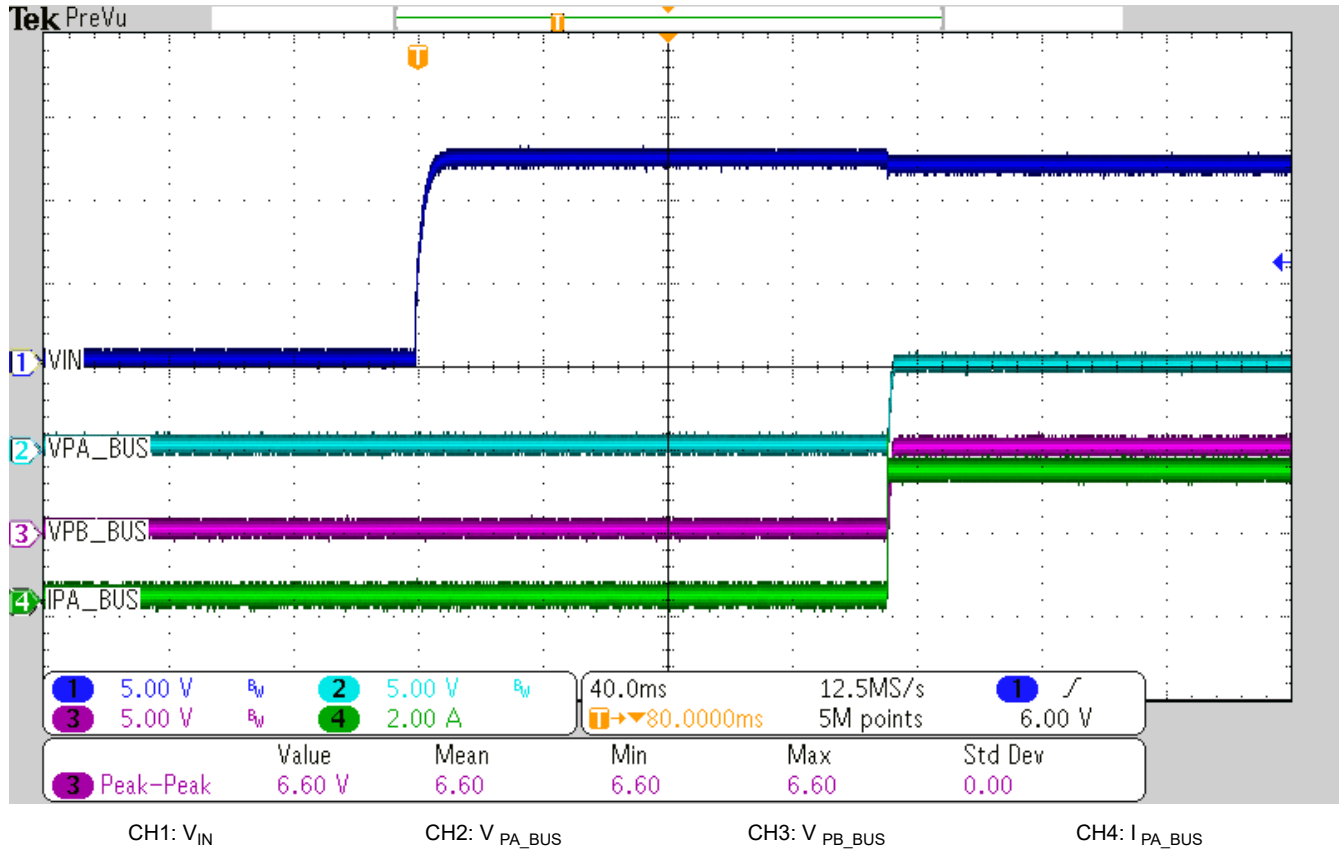


Figure 3-13. Power on

3.5 Undervoltage Protection

Undervoltage protection is shown in the following figure.

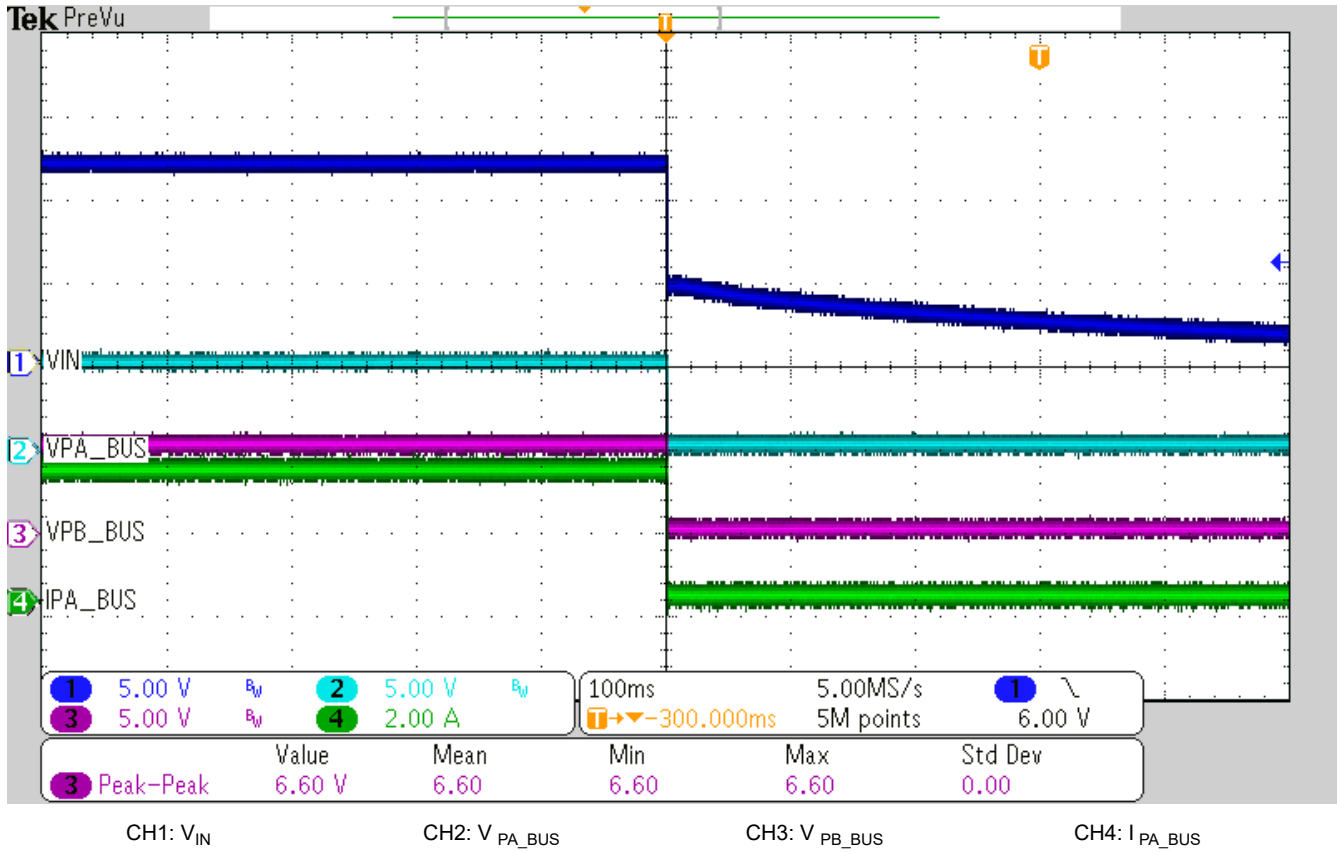


Figure 3-14. Power off

3.6 Thermal Management

The waveforms of thermal management are shown in following images. The temperature chamber is used to control the actual chip temperature, The thermal management function is triggered when the NTC temperature reaches 109.1°C (the chip temperature reaches 119.4°C), and the output voltage will reduce to 4.77 V. The thermal management function is turned off when the NTC resistor temperature drops to 93°C, and the output voltage will increase to 5.17 V.

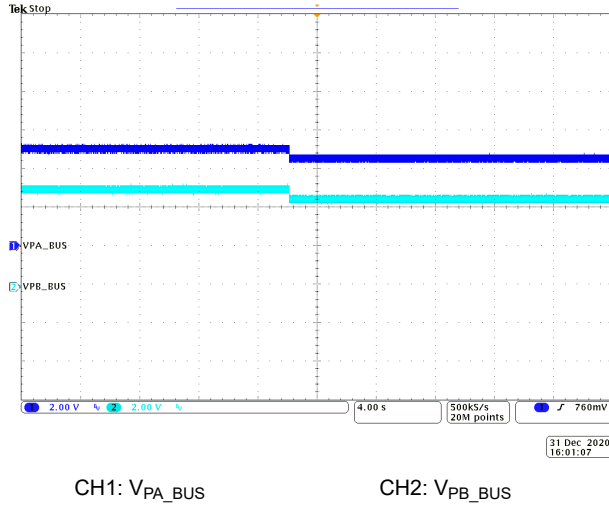


Figure 3-15. Thermal Management Function Turn on

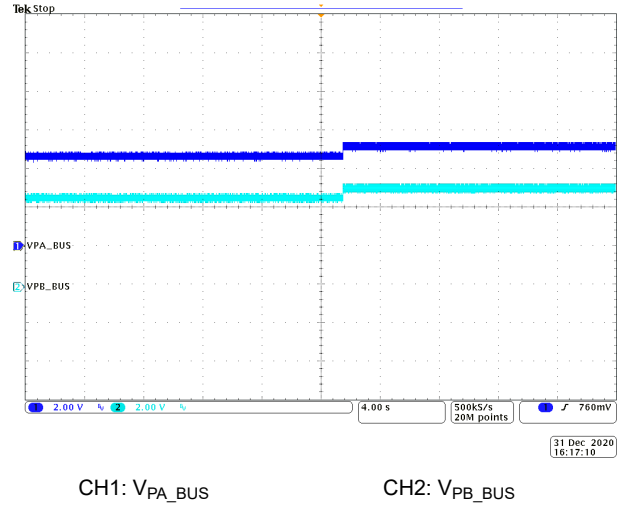


Figure 3-16. Thermal Management Function Turn off

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